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(54) Title: SUBSTRATE HANDLING DEVICE FOR A WAFER

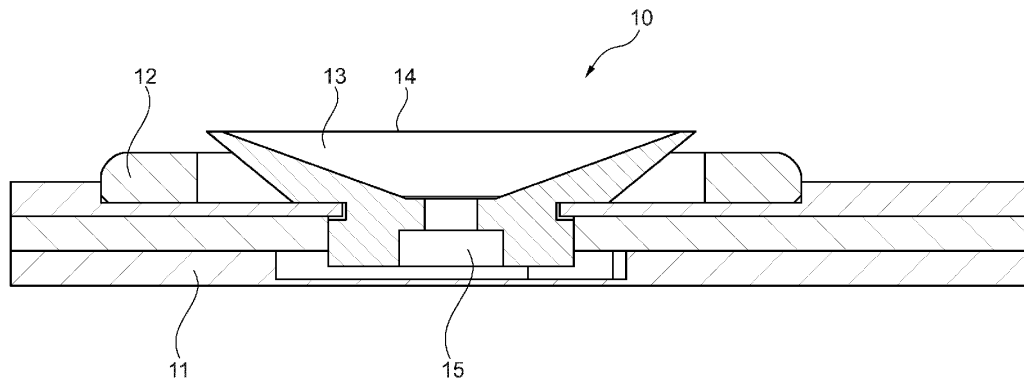


Fig. 1

(57) Abstract: The invention relates to a substrate handling device for a wafer, a substrate handling system for a wafer and a method for substrate handling. The substrate handling device comprises: - an end effector, - a straightening ring, and - a suction cup. The suction cup is arranged within the straightening ring. At least the straightening ring is releasably attached to the end effector. A first part of the suction cup is connectable to a vacuum supply and a second part of the suction cup is attachable to a substrate by means of reduced pressure provided by the vacuum supply. The suction cup projects from the straightening ring in a normal pressure state. The suction cup is on the same level as the straightening ring in a reduced pressure state, in which the substrate is held by the suction cup, so that the straightening ring contacts the substrate.

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